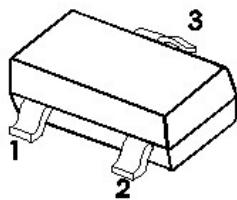
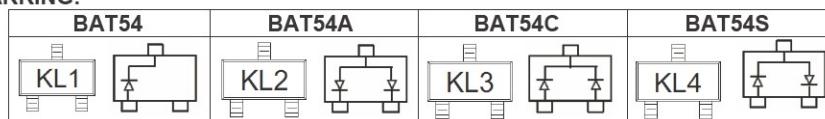


**SOT-23 Plastic-Encapsulate Schottky Barrier Diode****SOT-23****Features**

- High Current Capability
- Low Forward Voltage Drop
- Extremely Fast Switching Speed

**Mechanical Data**

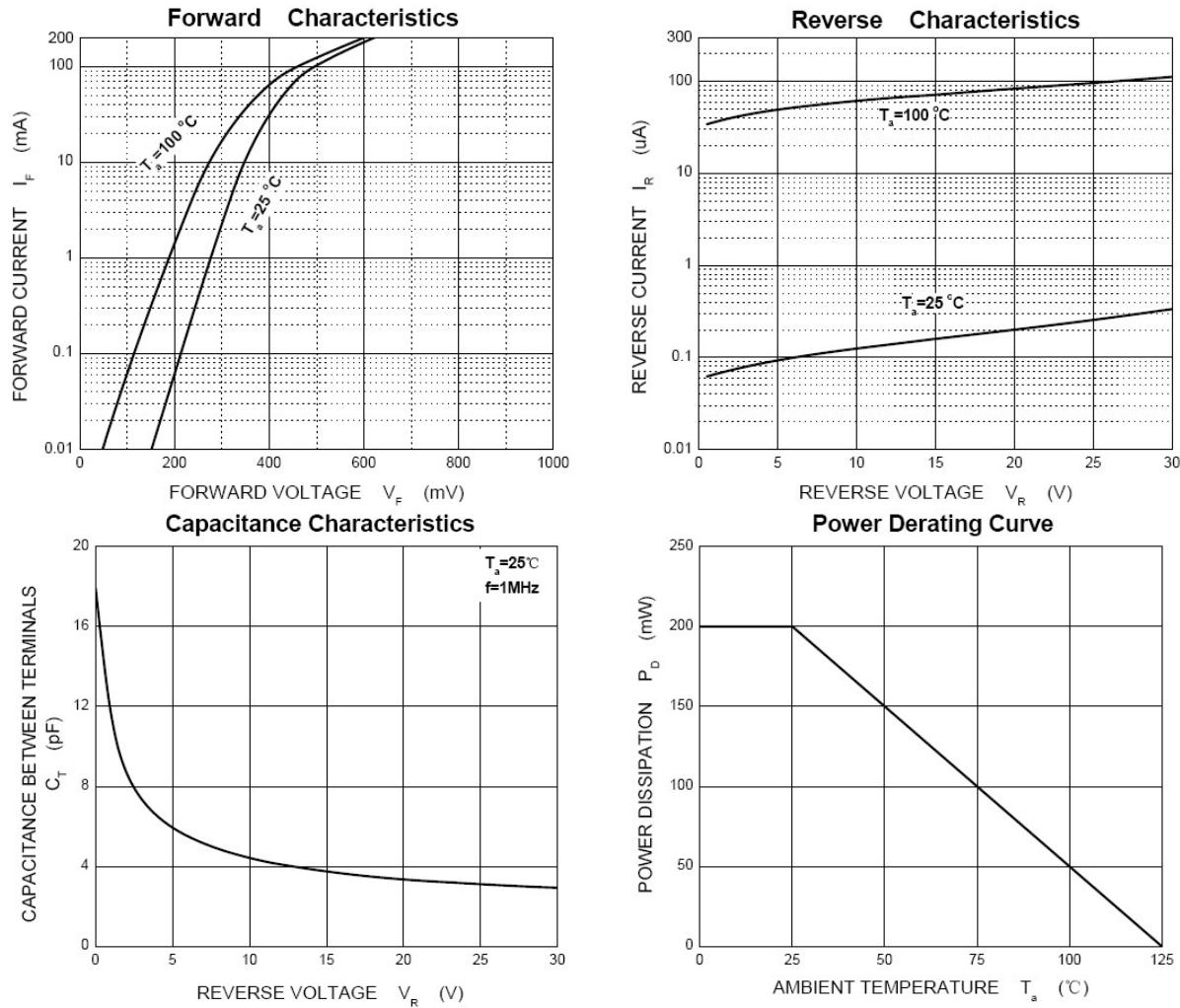
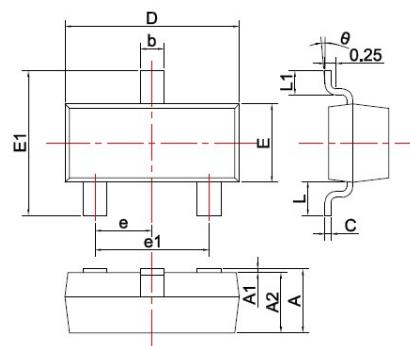
- SOT-23 Small Outline Plastic Package
- Epoxy UL: 94V-0
- Mounting Position: Any

**MARKING:****Maximum Ratings & Thermal Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified.)

Parameters	Symbol	Limit	Unit
Maximum repetitive peak reverse voltage	VRRM	30	V
Maximum RMS voltage	VRMS	21	V
Maximum DC blocking voltage	VDC	30	V
Maximum average forward rectified current	IFM	200	mA
Peak forward surge current 8.3 ms single half sine-wave	IFSM	600	mA
Typical thermal resistance	RθJA	500	°C/W
Power Dissipation	PD	200	mW
Junction Temperature	Tj	125	°C
Storage temperature range	TSTG	-50-+150	°C

**Electrical Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified).

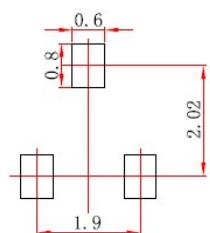
Parameters	Symbol	Test conditions	Min	Typ	Max	Unit
Maximum forward voltage	VF1	IF = 0.1mA			240	mV
	VF2	IF = 1.0mA			320	
	VF3	IF = 10mA			400	
	VF4	IF = 30mA			500	
	VF5	IF = 100mA			1000	
Maximum reverse breakdown voltage	VR	IR=100uA	30			V
Maximum reverse current	IR	VR=25V			2.0	uA
Type junction capacitance	C <sub>j</sub>	VR = 1.0V, f = 1MHz			10	pF
Reverse Recovery time	trr	IF=IR=10mA Irr=0.1XIR, RL=100Ω			5	ns

**Typical Characteristics****SOT-23 PACKAGE OUTLINE** Plastic surface mounted package

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
$\theta$	0°	8°

Unit: mm

PCB Design(Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs)



Note:  
 1. Controlling dimension: In millimeters.  
 2. General tolerance:  $\pm 0.05\text{mm}$ .  
 3. The pad layout is for reference purposes only.